

CPU

Select one

Ryzen AI 9 HX370

12C/24T

CPU is soldered down on **Bedrock RAI300 SoM** (System on Module)

RAM

Select one

No RAM
Requires applying thermal paste

8 GB
1x8 GB DDR5

16 GB
2x8 GB DDR5

32 GB
2x16 GB DDR5

64 GB
2x32 GB DDR5

RAM is **2x SODIMM DDR5**

Main storage

Select one

No main storage

960 GB PLP
Micron 7450
PLP: power loss protection
Gen 4

1 TB
Samsung 990 Pro
Gen 4

2 TB
Samsung 990 Pro
Gen 4

4 TB
Samsung 990 Pro
Gen 4

256 GB
ADATA 710
Gen 3

512 GB
ADATA 710
Gen 3

1 TB
ADATA 710
Gen 3

2 TB
ADATA 710
Gen 3

Additional storage devices can be installed.
See below **SX / PCIe x4 slot**

OS

Select one

No OS

Ubuntu Linux

Windows 11 IOT

NIO

Select one

NIO R8000 4X25
4x 2.5 GbE, USB4

NIO R7000 Basic
2x 2.5 GbE

NIO is **Networking & I/O** board

SX

Select one

No SX

SX 4M2
4x M.2 sockets

SX is **Storage & Extension Cards** board

PCle x4 slot 1

Select one

No device

960 GB PLP
Micron 7450
PLP: power loss protection
Gen 4

1 TB
Samsung 990 Pro
Gen 4

2 TB
Samsung 990 Pro
Gen 4

4 TB
Samsung 990 Pro
Gen 4

1 TB
ADATA 710
Gen 3

2 TB
ADATA 710
Gen 3

Hailo-8
AI acceleration module

PCle x4 slot 2

Select one

No device

960 GB PLP
Micron 7450
PLP: power loss protection
Gen 4

1 TB
Samsung 990 Pro
Gen 4

2 TB
Samsung 990 Pro
Gen 4

4 TB
Samsung EVO 990 Pro
Gen 4

1 TB
ADATA 710
Gen 3

2 TB
ADATA 710
Gen 3

Hailo-8
AI acceleration module

Modem

Select one

No modem

Customer's modem
M.2 key-B 3042 / 3052
USB 3.2
Requires antennas & SIM

LTE Cat 4
Quectel EM05-G
Requires antennas & SIM

LTE Cat 12
Quectel EM12-G
Requires antennas & SIM

5G
Quectel RM520N
Requires antennas & SIM

For antennas, see below **Enclosure / Top panel**
For SIM, see below **Enclosure / Rear panel**

PM

Select one

No PM
12V - 24V DC in

PM 1260
12V - 60V DC in

PM 1248
12V - 48V DC in

PM is **Power Module**

DCCON

Select one

DCCON Phoenix terminal

DCCON is **DC in Connector**

Enclosure

Select one

Without enclosure
requires customer's thermal design

Enclosure

No enclosure options

Walls

Select one

Tile
29x160x130 mm
Conduction cooling

60W enclosure
73x160x130 mm
Passive cooling

Front panel

Select one

Panel R7000 Basic
Required for NIO R7000 Basic

Panel R8000 4X25
Required for NIO R8000 4X25

Top panel

Select one

Generic top panel
No antennas

Top panel with antennas
Required for modem

Rear panel

Select one

Generic rear panel

Rear panel with SIM trays
Required for modem

Bottom panel

Select one

Generic bottom panel

Temperature

Select one

Commercial
0°C to 70°C

Industrial
-40°C to 85°C